

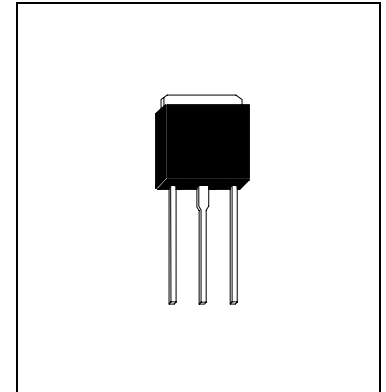


HI42C

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HI42C is designed for use in general purpose amplifier, low speed switching applications.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage -100 V
 - BVCEO Collector to Emitter Voltage -100 V
 - BVEBO Emitter to Base Voltage -5 V
 - IC Collector Current -6 A

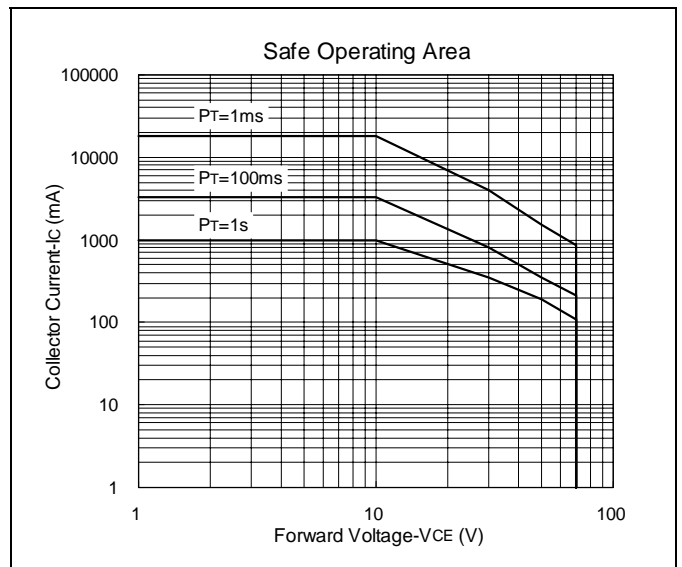
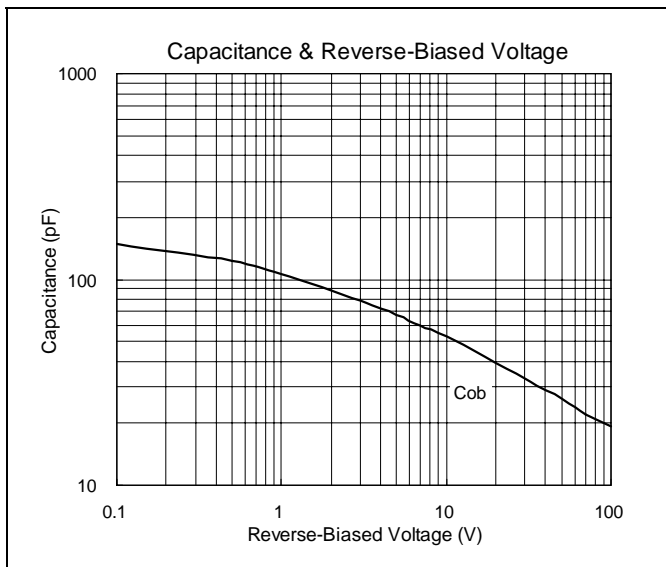
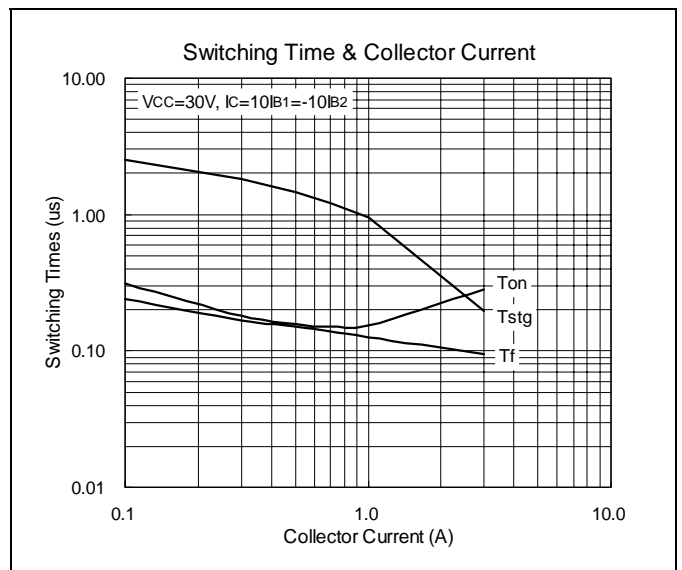
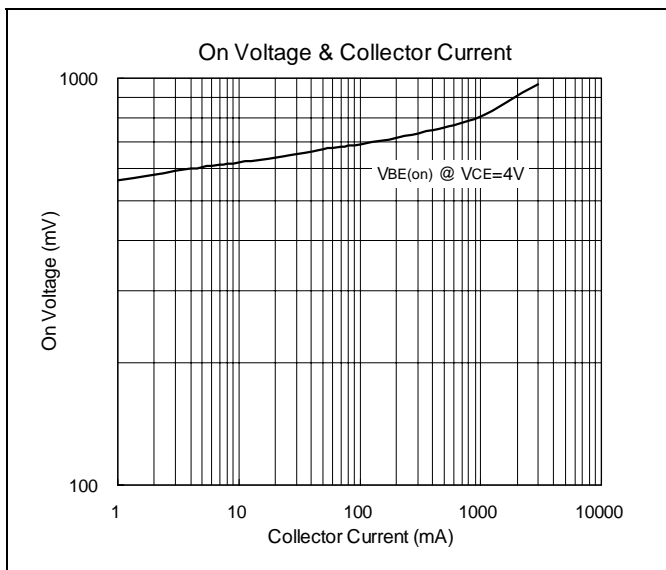
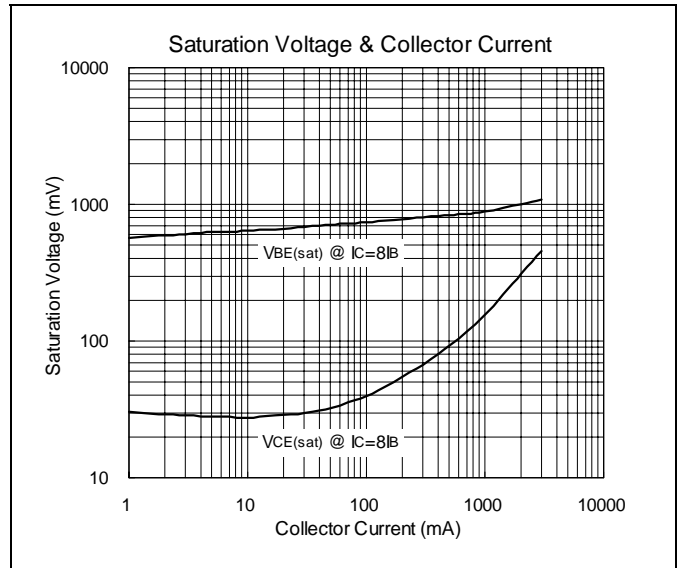
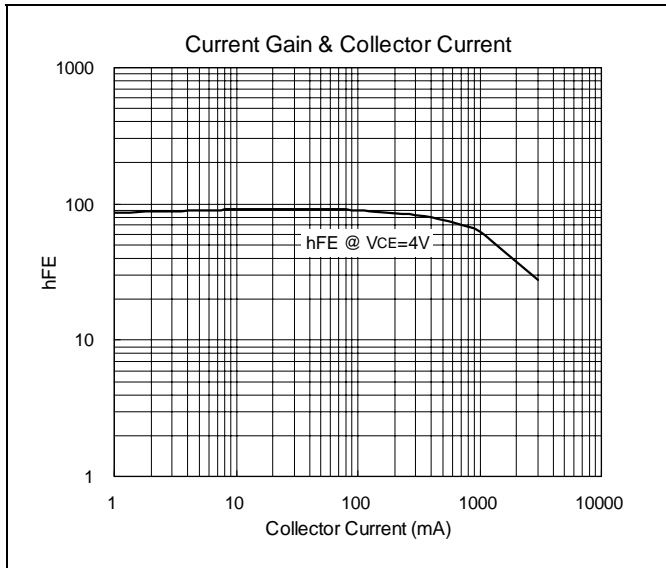
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA, IE=0
BVCEO	-100	-	-	V	IC=-30mA, IB=0
BVEBO	-5	-	-	V	IC=-100uA, IC=0
ICES	-	-	-10	uA	VCE=-100V, VEB=0
ICEO	-	-	-50	uA	VCE=-60V, IB=0
IEBO	-	-	-500	uA	VEB=-5V, IC=0
*VCE(sat)	-	-	-1.5	V	IC=-6A, IB=-600mA
*VBE(on)	-	-	-2	V	VCE=-4V, IC=-6A
*hFE1	30	-	-		VCE=-4V, IC=-300mA
*hFE2	15	-	75		VCE=-4V, IC=-3A
fT	3	-	-	MHz	VCE=-10V, IC=-500mA, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

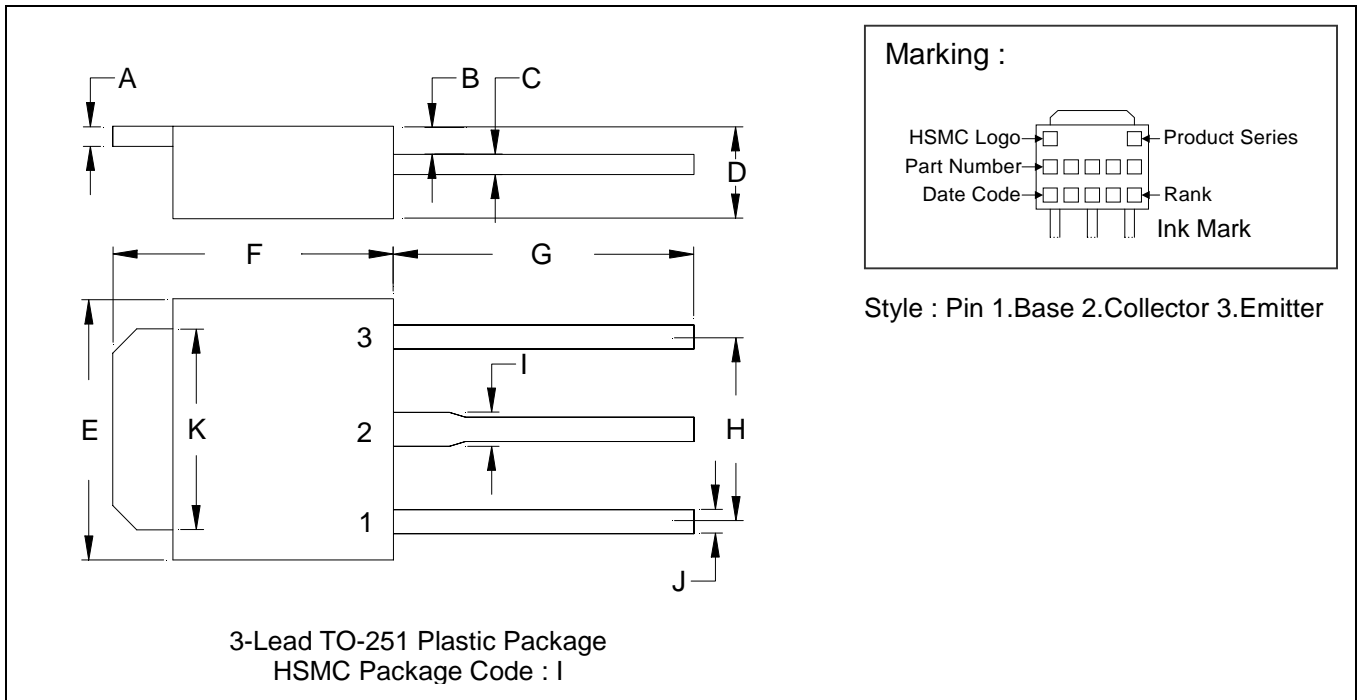


Characteristics Curve

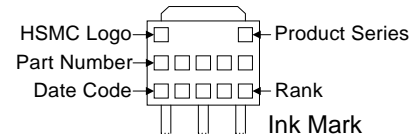




TO-251 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

- Notes :
- 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 - 2.Controlling dimension : millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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